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FDN86265P P-Channel PowerTrench[®] MOSFET -150 V, -0.8 A, 1.2 Ω

Features

- Max r_{DS(on)} = 1.2 Ω at V_{GS} = -10 V, I_D = -0.8 A
- Max $r_{DS(on)}$ = 1.4 Ω at V_{GS} = -6 V, I_D = -0.7 A
- Very low RDS-on mid voltage P-channel silicon technology optimised for low Qg
- This product is optimised for fast switching applications as well as load switch applications
- 100% UIL tested
- RoHS Compliant

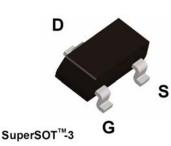


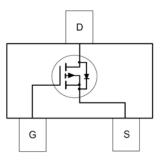
General Description

This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench[®] process that has been optimized for the on-state resistance and yet maintain superior switching performance.

Applications

- Active Clamp Switch
- Load Switch





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V _{DS}	Drain to Source Voltage		-150	V	
V _{GS}	Gate to Source Voltage		±25	V	
1	-Continuous	(Note 1a)	-0.8	•	
D	-Pulsed		-5	A	
E _{AS}	Single Pulse Avalanche Energy	(Note 3)	6	mJ	
P _D	Power Dissipation	(Note 1a)	1.5	w	
	Power Dissipation	(Note 1b)	0.6	VV	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics

$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case	(Note 1)	75	°C/W
$R_{ extsf{ heta}JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	80	0/10

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
265	FDN86265P	SSOT-3	7 "	8 mm	3000 units

May 2014

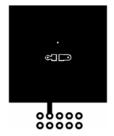
FDN86265P
P-Channel
PowerTrench ⁽⁾
[®] MOSFET

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	I _D = -250 μA, V _{GS} = 0 V	-150			V
$\Delta BV_{DSS} \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = -250 \ \mu\text{A}$, referenced to 25 °C		-129		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -120 V, V _{GS} = 0 V			-1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Chara	ICTERISTICS (Note 2)					
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \ \mu A$	-2	-3.3	-4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = -250 \ \mu$ A, referenced to 25 °C		5		mV/°C
		V _{GS} = -10 V, I _D = -0.8 A		0.85	1.2	1
r	Static Drain to Source On Resistance	$V_{GS} = -6 \text{ V}, \text{ I}_{D} = -0.7 \text{ A}$		0.96	1.4	Ω
rDS(on)		V _{GS} = -10 V, I _D = -0.8 A, T _J = 125 °C		1.54	2.2	- 52
9 _{FS}	Forward Transconductance	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -0.8 \text{ A}$		1.5		S
	Characteristics			450	010	- 5
Ciss	Input Capacitance	V _{DS} = -75 V, V _{GS} = 0 V,		158	210	pF
C _{oss}	Output Capacitance	f = 1 MHz		17	25 5	pF
C _{rss}	Reverse Transfer Capacitance Gate Resistance		0.1	1.6 3.3	6.7	pF Ω
R _g			0.1	5.5	0.7	52
	g Characteristics			6.7	10	
t _{d(on)}	Turn-On Delay Time Rise Time			5.7	12	ns
t _r	Turn-Off Delay Time	$V_{DD} = -75 \text{ V}, \text{ I}_{D} = -0.8 \text{ A},$ $V_{GS} = -10 \text{ V}, \text{ R}_{GEN} = 6 \Omega$		2.2 7.9	10 16	ns
t _{d(off)}	Fall Time	VGS = 10 V, KGEN = 0.12		9.9	20	ns
t _f Q _a	Total Gate Charge	$V_{} = 0 V t_{0} = 10 V$		9.9 2.9	4.1	ns nC
	Gate to Source Gate Charge	$V_{GS} = 0 V \text{ to -10 V}$ $V_{DD} = -75 V,$		0.8	7.1	nC
Q _{gs} Q _{gd}	Gate to Drain "Miller" Charge	I _D = -0.8 A		0.8		nC
Ƴgd	Sate to Brain Willer Onarge			0.0	I	
	urce Diode Characteristics					
V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 V, I_S = -0.8 A$ (Note 2)		-0.86	-1.3	V

Electrical Characteristics $T_J = 25 \text{ °C}$ unless otherwise noted

V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 V, I_S = -0.8 A$ (Note 2)	-0.86	-1.3	V
t _{rr}	Reverse Recovery Time	Ic = -0.8 A. di/dt = 100 A/us		ns	
Q _{rr}	Reverse Recovery Charge	$T_{F} = -0.6 \text{ A}, \text{ avat} = 100 \text{ A/}\mu\text{s}$	70	112	nC

Notes: 1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



2. Pulse Test: Pulse Width < 300 $\mu s,$ Duty cycle < 2.0%.

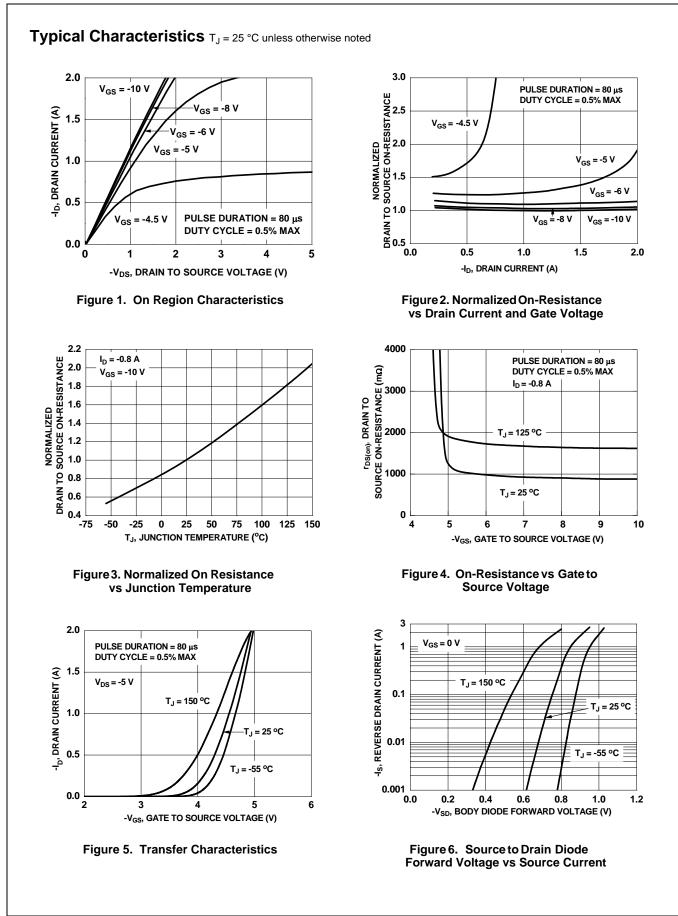
a) 80 °C/W when mounted on a 1 in² pad of 2 oz copper

3. Starting T_J = 25 °C; N-ch: L = 3 mH, I_{AS} = -2 A, V_{DD} = -150 V, V_{GS} = -10 V. 100% test at L = 0.1 mH, I_{AS} = -9 A.

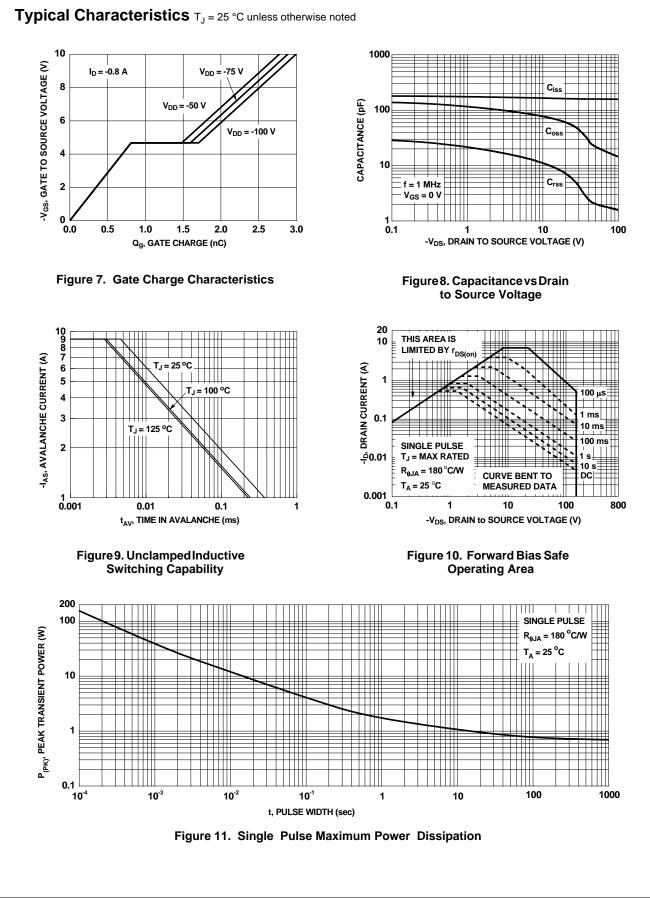


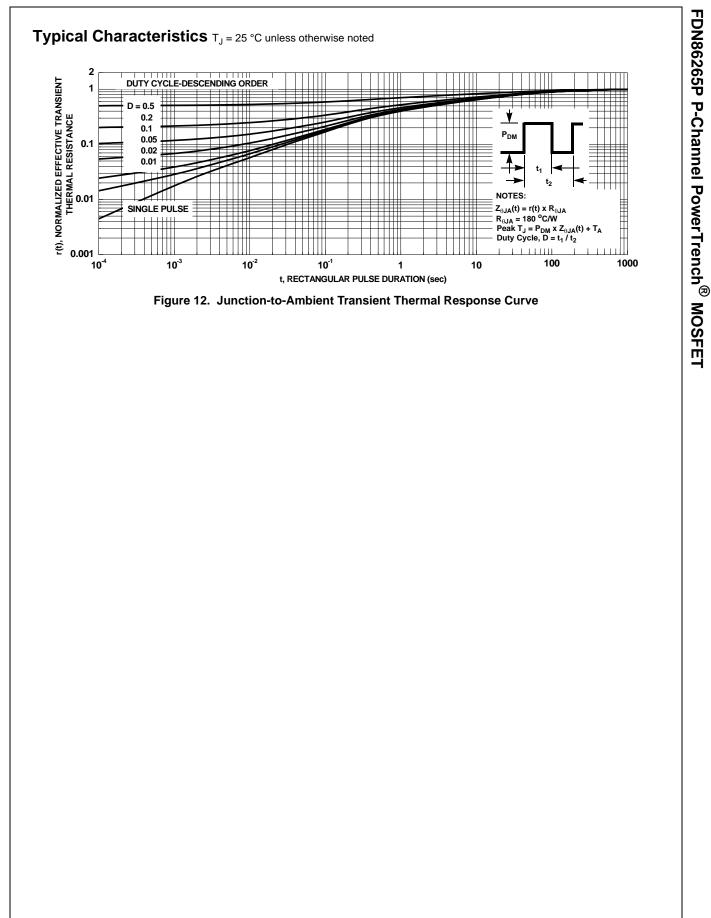
b) 180 °C/W when mounted on a minimum pad.

2











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	Formative / In Design First Production Full Production		

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